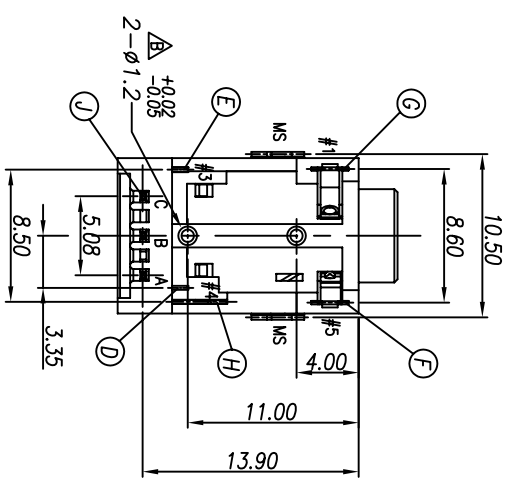
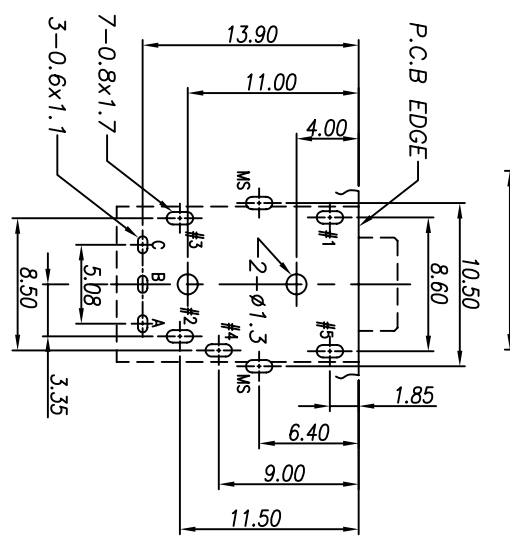
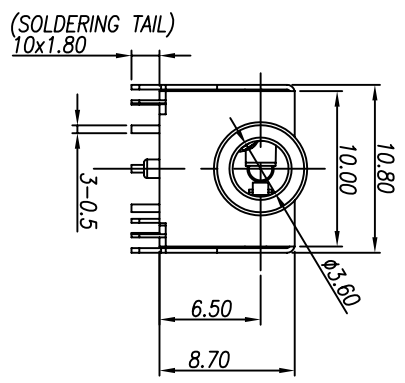
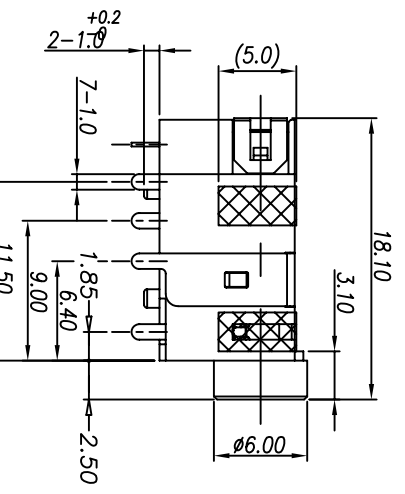
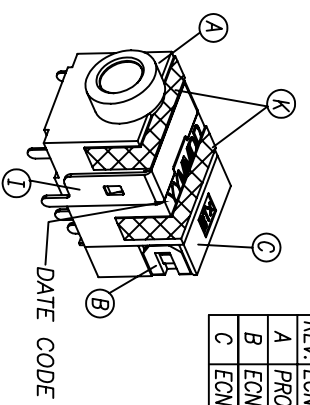
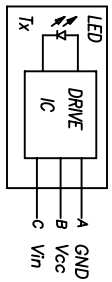
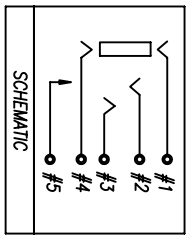
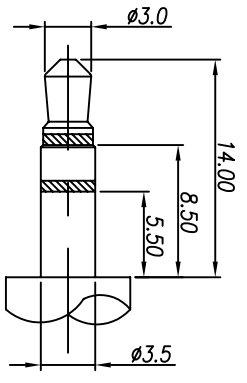
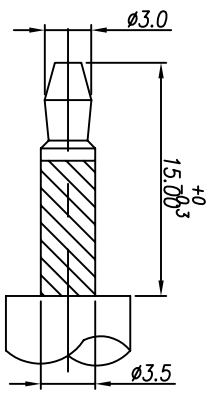


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	LMO	2007.03.22
B	ECN NO:1070206	LMO	2007.07.04
C	ECN NO:1070334	AMY	2007.12.20



- SPECIFICATIONS:**
- 1. ELECTRICAL CHARACTERISTICS:**
- 1-1. RATING: 12V 1A
  - 1-2. CONTACT RESISTANCE: 30mΩMAX(BEFORE).
  - 1-3. DIELECTRIC VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE
  - 1-4. INSULATION RESISTANCE: 100M MIN. (MEASURED BY 500 VDC)
- 2. MECHANICAL CHARACTERISTICS:**
- 2-1. INSERTED FORCE : 3.5 KGS MAX.
  - 2-2. WITHDRAWAL FORCE : 0.3~4.0 KGS
- 3. LIFE TEST: 5,000 CYCLES MIN.
  - 4. PACKAGING: TAPE & REEL
  - 5. TO CONFORM TO THE SINGATRON HSF SPEC.
  - 6. GREEN PRODUCT IDENTIFICATION MARK ON JACK:
  - 7. GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING:
  - 8. FOR LEAD-FREE PROCESS.

RECOMMENDED PCB LAYOUT  
SOLDER SIDE (Tolerance:±0.05)



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	COVER	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK COLOR
B	COVER	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK COLOR
C	CASE	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK COLOR
D	RING SPRING	1	PHOSPHOR BRONZE	GOLD FLASH
E	TIP SPRING	1	PHOSPHOR BRONZE	GOLD FLASH
F	EARTH TERMINAL	1	PHOSPHOR BRONZE	GOLD FLASH
G	EARTH SPRING-A	1	PHOSPHOR BRONZE	GOLD FLASH
H	EARTH SPRING-B	1	PHOSPHOR BRONZE	GOLD FLASH
I	SHIELDING	1	BRASS	TIN PLATING (Lead-Free) TIN PLATING 600 °ON SOLDER TIN ALL OVER NICKEL PLATING.
J	IC DRIVE	1	EPOXY	N/A
K	INSULATION FILM	2	MYLAR	N/A

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

TITLE: Ø3.5 PHONE JACK (WITH IC)

DWN: #1001121 PART NO. 2SI-E373-0A1

CHKD: LW 2007.12.1 SCALE: 3/1 UNIT: mm

APVD: WBL 2007.12.1 SIZE: A3 SHEET: 1 OF 1 REV: C

CUSTOMER COPY